



应用范围

适用于设备制造、运输传送、提升台等工业环境；
具有较好的恢复力。

APPLICATIONS

With good restoring ability, suitable for such industrial applications as equipment manufacturing, transport and conveyance, lifting platform.

电线结构

多股细裸束绞铜丝或镀锡铜丝导体；
TPE绝缘，特殊PVC护套。

WIRE MAKE-UP

Fine bare copper/tinned copper stranded conductor
TPE insulation, special PVC sheath

技术参数

- ① 温度范围：固定安装 $-10^{\circ}\text{C} \sim +50^{\circ}\text{C}$
移动安装 $0^{\circ}\text{C} \sim +50^{\circ}\text{C}$
- ② 额定电压：U₀/U 300/500V
- ③ 符合标准：EEC规程73/23(低电压规程)CE
- ④ 导体标准：VDE 0295/IEC 60228 5类

TECHNICAL DATA

- ① Operating Temp.:
 $-10^{\circ}\text{C} \sim +50^{\circ}\text{C}$ for fixed wiring
 $-0^{\circ}\text{C} \sim +50^{\circ}\text{C}$ for movable wiring
- ② Rated Voltage: U₀/U 300/500V
- ③ Governing Standards: CE 73/23 EEC (Low voltage directive)
- ④ Conductor Standards: Category 5 in VDE 0295/IEC 60228

导体截面 Cross Section 芯数 × mm ² Core. No. × mm ²	导体结构 Conductor Structure 芯数 × 根数/单根直径 Core. No. × Cond. No./O.D	螺旋外径 Spiral Diameter 近似 mm	螺旋长度 Spiral Length. 近似 mm	最大拉伸长度 Max. Length 近似 mm	连接末端 Conn. Terminal 近似 mm	环境温度 30℃架空时 参考载流量(A) Ambient (aerial cable)
7 × 0.75	7 × 24/0.20	30	500	1200	300	
7 × 0.75	7 × 24/0.20	30	1000	2500	300	
7 × 0.75	7 × 24/0.20	30	1500	3700	300	
7 × 0.75	7 × 24/0.20	30	2000	5000	300	
12 × 0.75	12 × 24/0.20	40	500	1200	300	
12 × 0.75	12 × 24/0.20	40	1000	2500	300	
12 × 0.75	12 × 24/0.20	40	1500	3700	300	
12 × 0.75	12 × 24/0.20	40	2000	5000	300	
3 × 1.5	3 × 30/0.25	30	500	1200	300	8
3 × 1.5	3 × 30/0.25	30	1000	2500	300	8
3 × 1.5	3 × 30/0.25	30	1500	3700	300	8
3 × 1.5	3 × 30/0.25	30	2000	5000	300	8
4 × 1.5	4 × 30/0.25	35	500	1200	300	7
4 × 1.5	4 × 30/0.25	35	1000	2500	300	7
4 × 1.5	4 × 30/0.25	35	1500	3700	300	7
4 × 1.5	4 × 30/0.25	35	2000	5000	300	7
5 × 1.5	5 × 30/0.25	40	500	1200	300	
5 × 1.5	5 × 30/0.25	40	1000	2500	300	
5 × 1.5	5 × 30/0.25	40	1500	3700	300	
5 × 1.5	5 × 30/0.25	40	2000	5000	300	

▲ 载流量是周围温度设定在30℃时的计算值。电线芯数、周围温度、布线状况等条件改变时应乘以系数。(见附录)

▲ Current-carrying capacity is the calculated value based on a ambient temperature of 30℃ and is to be multiplied by a factor when application conditions including number of cores, ambient temperature and wiring condition are changed. (see Appendix)